

SN54HC237, SN74HC237
3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS
WITH ADDRESS LATCHES

D2804, MARCH 1984—REVISED JUNE 1989

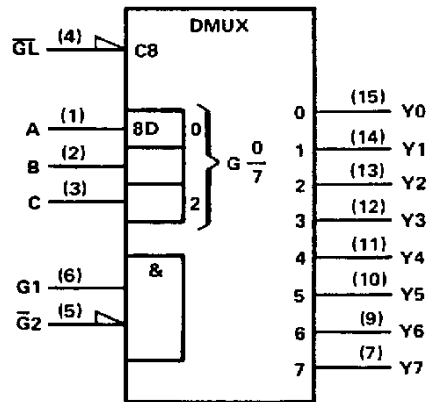
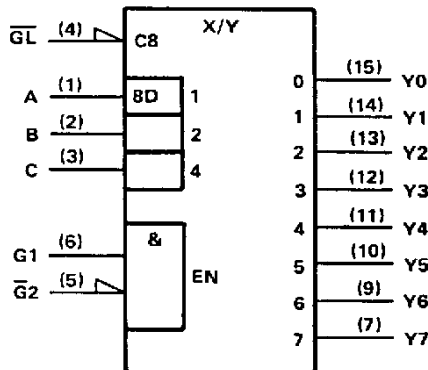
- Combines Decoder and 3-Bit Address Latch
- Incorporates 2 Output Enables to Simplify Cascading
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

description

The 'HC237 is a three-line to eight-line decoder/demultiplexer with latches on the three address inputs. When the latch-enable (\overline{GL}) is low, the 'HC237 acts as a decoder/demultiplexer. When \overline{GL} goes from low to high, the address present at the select inputs (A, B, and C) is stored in the latches. Further address changes are ignored as long as \overline{GL} remains high. The output enable controls, G1 and $\overline{G2}$, control the outputs independently of the select or latch-enable inputs. All of the outputs are forced low if G1 is low or $\overline{G2}$ is high. The 'HC237 is ideally suited for implementing glitch-free decoders in strobed (stored-address) applications in bus-oriented systems.

The SN54HC237 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74HC237 is characterized for operation from -40°C to 85°C .

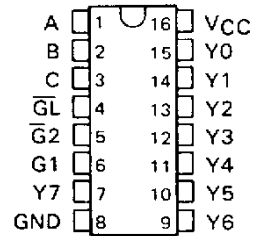
logic symbols (alternatives)†



†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, and N packages.

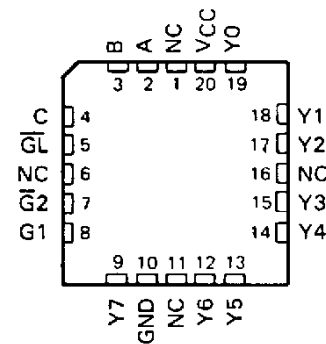
SN54HC237 . . . J PACKAGE
 SN74HC237 . . . D† OR N PACKAGE

(TOP VIEW)



SN54HC237 . . . FK PACKAGE

(TOP VIEW)



NC—No internal connection

†Contact the factory for D availability.

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

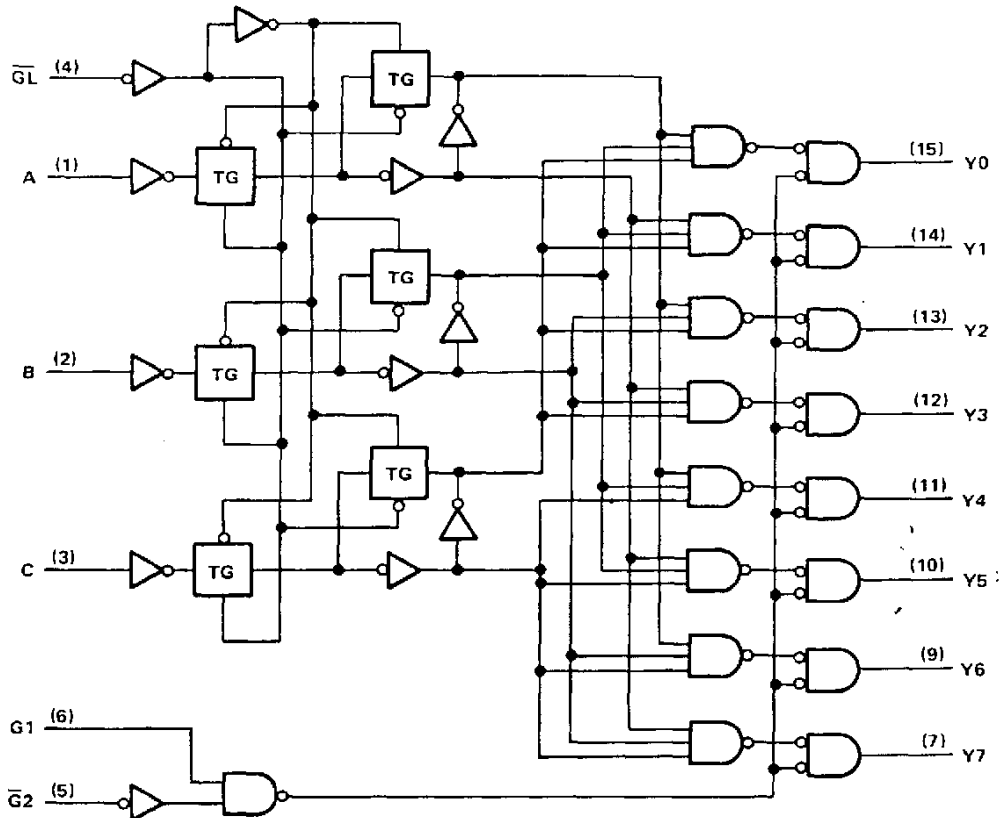


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logic diagram (positive logic)



Pin numbers shown are for D, J, and N packages.

FUNCTION TABLE

ENABLE			SELECT			OUTPUTS							
GL	G1	G2	C	B	A	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
X	X	H	X	X	X	L	L	L	L	L	L	L	L
X	L	X	X	X	X	L	L	L	L	L	L	L	L
L	H	L	L	L	L	H	L	L	L	L	L	L	L
L	H	L	L	L	H	L	H	L	L	L	L	L	L
L	H	L	L	H	L	L	L	H	L	L	L	L	L
L	H	L	L	H	H	L	L	L	L	H	L	L	L
L	H	L	H	L	H	L	L	L	L	L	H	L	L
L	H	L	H	H	L	L	L	L	L	L	L	H	L
L	H	L	H	H	H	L	L	L	L	L	L	L	H
H	H	L	X	X	X	Outputs corresponding to stored address, L; all others, H							

TEXAS
INSTRUMENTS

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absolute maximum ratings over operating free-air temperature range†

Supply voltage, V_{CC}	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND pins	± 50 mA
Lead temperature 1,6 mm (1/16 in) from case for 60 s: FK or J package	300°C
Lead temperature 1,6 mm (1/16 in) from case for 10 s: D or N package	260°C
Storage temperature range	-65°C to 150°C

†Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54HC237			SN74HC237			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	2	5	6	2	5	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V	1.5		1.5			V
		$V_{CC} = 4.5$ V	3.15		3.15			
		$V_{CC} = 6$ V	4.2		4.2			
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V	0	0.3	0	0.3		V
		$V_{CC} = 4.5$ V	0	0.9	0	0.9		
		$V_{CC} = 6$ V	0	1.2	0	1.2		
V_I	Input voltage	0	V_{CC}		0	V_{CC}		V
V_O	Output voltage	0	V_{CC}		0	V_{CC}		V
t_t	Input transition (rise and fall) times	$V_{CC} = 2$ V	0	1000	0	1000		ns
		$V_{CC} = 4.5$ V	0	500	0	500		
		$V_{CC} = 6$ V	0	400	0	400		
T_A	Operating free-air temperature	-55	125		-40	85		°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC237		SN74HC237		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	$V_I = V_{IH}$ or V_{IL} , $I_{OH} = -20 \mu\text{A}$	2 V	1.9	1.998		1.9		1.9	V	
		4.5 V	4.4	4.499		4.4		4.4		
		6 V	5.9	5.999		5.9		5.9		
V_{OL}	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 20 \mu\text{A}$	2 V		0.002	0.1		0.1		0.1	V
		4.5 V		0.001	0.1		0.1		0.1	
		6 V		0.001	0.1		0.1		0.1	
V_{OL}	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	V
		6 V		0.15	0.26		0.4		0.33	
		6 V		± 0.1	± 100		± 1000		± 1000	
I_I	$V_I = V_{CC}$ or 0	6 V							nA	
I_{CC}	$V_I = V_{CC}$ or 0, $I_O = 0$	6 V			8	160		80	μA	
C_i		2 to 6 V		3	10		10		10	pF



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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

	V _{CC}	T _A = 25°C			SN54HC237		SN74HC237		UNIT
		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _w Pulse duration, \overline{GL} low	2 V	80			120		100	ns	
	4.5 V	16			24		20		
	6 V	14			20		17		
t _{su} Setup time, A, B, or C before $\overline{GL}\uparrow$	2 V	75			115		95	ns	
	4.5 V	15			23		19		
	6 V	13			20		16		
t _h Hold time, A, B, and C after $\overline{GL}\uparrow$	2 V	5			5		5	ns	
	4.5 V	5			5		5		
	6 V	5			5		5		

switching characteristics over recommended operating free-air temperature range (unless otherwise noted), C_L = 50 pF (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC237		SN74HC237		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A, B, C	Any	2 V		91	190		285		240	ns
			4.5 V		23	38		57		48	
			6 V		17	32		48		41	
t _{pd}	$\overline{G2}$	Any	2 V		66	145		220		181	ns
			4.5 V		18	29		44		36	
			6 V		13	25		37		31	
t _{pd}	G1	Any	2 V		68	145		220		181	ns
			4.5 V		18	29		44		36	
			6 V		14	25		37		31	
t _{pd}	\overline{GL}	Any	2 V		92	190		285		240	ns
			4.5 V		24	38		57		48	
			6 V		19	32		48		41	
t _t		Any	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

C _{pd}	Power dissipation capacitance	No load, T _A = 25°C	85 pF typ
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NOTE 1: Load circuit and voltage waveforms are shown in Section 1.



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-88606012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SN74HC237N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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